

1) Internal photographs can not simply be held confidential. Further justification must be provided before confidentiality can be granted on these exhibits. Additionally, if only certain pages of this exhibit are to be held confidential, then the exhibit must be separated into 2 parts, one not held confidential, and one that is.

The internal photographs are requested as confidential as the DUT radome is epoxy sealed to the device, and cannot be removed without damage to the device. Previous filings of similar radar systems have held this as sufficient justification to keep all internal photographs confidential.

2) The parts list provided does not appear to be covered by confidentiality. Please confirm or correct the confidentiality exhibit.

The confidentiality exhibit has been corrected and re-uploaded.

3) Peak power appears to be possible to +5 dBm per the 2nd page of the block diagram. This is much different than expected. Please explain and/or fix.

The 5 dBm value in the equipment specification is a design source specification that does not account for loss in the system (antenna losses and interconnect transmission line losses). The EIRP, as computed in the test report from measured radiated emissions, is a more accurate method of determining the power rating of the DUT, since antenna efficiency and transmission line losses are not directly provided.

4) Is a photograph of the PCB layout Photo-2 (RF-unit solder-side ) available without the metal "bar" across the board?

A photograph has been requested, and if available that photo will be provided. However, please note that this particular metal assembly is the mounting structure / heatsink of the MMIC, and separation of the ground metal from the device will likely destroy the MMIC. (This may be likened to removing the packaging from an IC.) No recognizable components will lie between the metal structure and the MMIC wafer, as this structure simply acts as a heatsink for the components within the MMIC structure.

5) It appears that only part of the RF schematics may have been provided. Please explain and/or provide as necessary.

A request has been made with the manufacturer for more complete schematics of the RF subsection, and if available they will be provided. However, much of the high frequency RF sub-system is enclosed in the MMIC device; custom manufactured for this application and pre-packaged as the PCB RF UNIT. Since, in general, RF schematics of commercial RFIC's are not required during certification (only block diagram information), it may be expected that the

schematics for a similar MMIC structure (which may be the property of a third party vendor) also would not be required. Please comment on the requirement for RF schematics of RFIC's and MMIC's during the certification process so that we may proceed in acquiring the schematics requested.

7) The application form specifies D1N emissions, while the block diagram page 2, and the FCC application shows P0N and QXN. Please provide justification for the emissions designator.

A corrected IC application form has been uploaded.

Thank you